

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-064272
 (43)Date of publication of application : 28.02.2002

(51)Int.Cl. H05K 3/46
 H05K 3/40

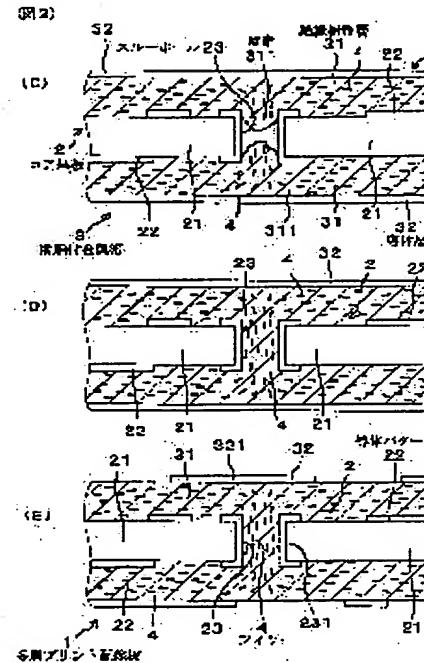
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 (22)Date of filing : 16.08.2000 (72)Inventor : MIKADO YUKINOBU

(54) MULTILAYERED PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayered printed wiring board which surely prevents the occurrence of disconnection and short-circuiting and is superior in production efficiency, and to provide a manufacturing method.

SOLUTION: In the method for manufacturing the multilayer printed wiring board 1, resinous metal foils 3, which are obtained by sticking insulating resin layers 31 and conductor layers 32, are laminated on both faces of a core substrate, where a through-hole 23 has been made. The insulating resin layer 31 of resin metallic foil 3 is constituted of a resin 311, to which filler 4 is mixed. At lamination of resin metal foil 3 to the core substrate 2, the resin 311 of the insulating resin layer 31 is made to flow into the through-hole 23 of the core substrate 2 and the hole is filed with resin.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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